Abstract:

Semiconductor wafers with highly precise edge profile and method for producing them

The subject matter of the invention is a semiconductor wafer having a front side, a rear side and an edge which runs along the circumference of the semiconductor wafer and which connects the front side and the rear side and which has a defined edge profile, the edge profile being substantially constant over the entire circumference of the semiconductor wafer.

The subject matter of the invention is also a multiplicity of semiconductor wafers, the edge profile being substantially constant from semiconductor wafer to semiconductor wafer.

The subject matter of the invention is also a method for producing semiconductor wafers of this type.

Fig. 1